

TITLE

VOLATILE COPPER(I) COMPLEXES FOR DEPOSITION OF COPPER
FILMS BY ATOMIC LAYER DEPOSITION

ABSTRACT

5 The present invention relates to novel 1,3-diimine copper
complexes and the use of 1,3-diimine copper complexes for the deposition
of copper on substrates or in or on porous solids in an Atomic Layer
Deposition process.

10

15

20

25

30

35

BCS/dmm